

# BobWillisOnline.com

Our web based seminars represent an efficient way for you and your team to develop practical knowledge, delivering expert advice and guidance to you when and where you choose. Simple webinars offer a low cost and time efficient training option. The online seminars and video library can be accessed from the internet, eliminating the need to take time out of the office and avoid expensive travel costs



The following are a small selection of the topics we can offer you and your company

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| Modern PCB Assembly Process – Management Overview            | Flexible Circuit Assembly, Rework with Lead-Free Alloys         |
| Printed Circuit Board Manufacture – Management Overview      | Vapour Phase or Convection Reflow – Selecting the Right Process |
| PCB Manufacture & Assembly for Purchasing Executives         | PCB Surface Finishes Selection & Process Issues                 |
| Package on Package PoP Assembly Process & Inspection         | BGA Design & Assembly Implementation                            |
| PCB Assembly Failure Analysis - How to Do It?                | Double Sided & Simultaneous Double Sided Reflow Soldering       |
| BGA Dye & Pry Inspection - How to Do It?                     | Pin In Hole Intrusive Reflow - How to Do It?                    |
| BGA Optical & X-Ray Inspection Criteria                      | Selective Soldering, Design & Process Control Requirements      |
| Conformal Coating Application & Inspection Procedures        | NPI Introduction Procedures, Yield Determination & Improvements |
| Crimp Connection Inspection & Quality Control Implementation | Ball Grid Array Rework – How to Do It                           |
| Introduction to Wave Soldering for Lead-Free                 | Design for Manufacture Review Procedures                        |
| Stencil Design, Inspection & Quality Control in Manufacture  | Wave Solder In Process Control Procedures                       |
| Counterfeit Component Inspection Methods                     | Lead-Free Temperature Profiling - How to Do It?                 |
| Troubleshooting Your Assembly Yields – On site and Offshore  | Lead-Free Process Problems & Failure Modes                      |
| QFN/LGA Assembly & Inspection Criteria                       | Printed Circuit Board Problems & Failure Modes                  |
| 0201-01005 Design, Assembly & Inspection Processes           | Monitoring & Comparing PPM Yields in Production                 |
|  | Hand Soldering & Desoldering with Lead-Free Solder              |

*“Training where, when and how you want it”*

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